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- Operate With 3-V to 5.5-V V<sub>CC</sub> Supply
- Operate Up To 1 Mbit/s
- Low Standby Current . . . 1 μA Typ
- External Capacitors . . . 4  $\times$  0.1  $\mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply
- RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)
- Auto-Powerdown Feature Automatically Disables Drivers for Power Savings
- Applications
  - Battery-Powered, Hand-Held, and Portable Equipment
  - PDAs and Palmtop PCs
  - Notebooks, Sub-Notebooks, and Laptops
  - Digital Cameras
  - Mobile Phones and Wireless Devices

#### description/ordering information

**DB OR PW PACKAGE** (TOP VIEW) EN 16 FORCEOFF 15 VCC C1+ [ 2 14 GND V+ 13 13 DOUT  $C1 - \Pi 4$ 12 FORCEON C2+ [ 5 C2-Π6 11 DIN V− **Π**7 10 INVALID 9 ROUT RIN 8

The SN65C3221 and SN75C3221 consist of one line driver, one line receiver, and a dual charge-pump circuit with  $\pm$ 15-kV ESD protection pin to pin (serial-port connection pins, including GND). These devices provide the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. These devices operate at data signaling rates up to 1 Mbit/s and a driver output slew rate of 24 V/µs to 150 V/µs.

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the devices do not sense a valid RS-232 signal on the receiver input, the driver output is disabled. If FORCEOFF is set low and EN is high, both the driver and receiver are shut off, and the supply current is reduced to 1  $\mu$ A. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to the receiver input. The INVALID output notifies the user if an RS-232 signal is present at the receiver input. INVALID is high (valid data) if the receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30  $\mu$ s. Refer to Figure 5 for receiver input levels.

TA	PACKAG	Eţ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP (DB)	Reel of 2000	SN75C3221DBR	CA3221
–0°C to 70°C	T0000 (DMA)	Tube of 90	SN75C3221PW	040004
	TSSOP (PW)	Reel of 2000	SN75C3221PWR	CA3221
	SSOP (DB)	Reel of 2000	SN65C3221DBR	CB3221
–40°C to 85°C	TOOOD (DW)	Tube of 90	SN65C3221PW	000004
	TSSOP (PW)	Reel of 2000	SN65C3221PWR	CB3221

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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**Function Tables** 

			EACH DRIVER		
		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Х	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	Х	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

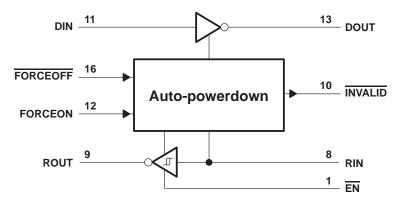
H = high level, L = low level, X = irrelevant, Z = high impedance

EACH RECEIVER

	INPUTS				
RIN	EN	VALID RIN RS-232 LEVEL	OUTPUT ROUT		
L	L	Х	Н		
н	L	х	L		
Х	Н	Х	Z		
Open	L	No	н		

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = disconnected input or connected driver off

logic diagram (positive logic)





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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> (see Note 1) Positive output supply voltage range, V+ (see Note 1) Negative output supply voltage range, V– (see Note 1)	–0.3 V to 7 V
Supply voltage difference, $V + - V -$ (see Note 1)	
Input voltage range, $V_1$ : Driver (FORCEOFF, FORCEON, EN)	
Receiver	
Output voltage range, V <sub>O</sub> : Driver	13.2 V to 13.2 V
Receiver (INVALID)	–0.3 V to V <sub>CC</sub> + 0.3 V
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3): DB package	
PW package	108°C/W
Operating virtual junction temperature, T <sub>J</sub>	150°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

- 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 4 and Figure 6)

			MIN	NOM	MAX	UNIT
Supply voltage		V <sub>CC</sub> = 3.3 V	3	3.3	3.6	
		$V_{CC} = 5 V$	4.5	5	5.5	V
IH Driver and control high-level input voltage		$V_{CC} = 3.3 V$	2			
	DIN, FORCEOFF, FORCEON, EN	$V_{CC} = 5 V$	2.4			V
Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON, EN				0.8	V
Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
Receiver input voltage			-25		25	V
			-40		85	
Operating tree-air temperature		SN75C3221	0		70	°C
	Driver and control high-level input voltage Driver and control low-level input voltage Driver and control input voltage	Driver and control high-level input voltage DIN, FORCEOFF, FORCEON, EN   Driver and control low-level input voltage DIN, FORCEOFF, FORCEON, EN   Driver and control input voltage DIN, FORCEOFF, FORCEON, EN   Receiver input voltage DIN, FORCEOFF, FORCEON	Supply voltage $V_{CC} = 5 V$ Driver and control high-level input voltage DIN, FORCEOFF, FORCEON, EN $V_{CC} = 3.3 V$ Driver and control low-level input voltage DIN, FORCEOFF, FORCEON, EN $V_{CC} = 5 V$ Driver and control input voltage DIN, FORCEOFF, FORCEON, EN V   Driver and control input voltage DIN, FORCEOFF, FORCEON EN   Receiver input voltage SN65C3221	Supply voltage $V_{CC} = 3.3 \text{ V}$ 3   V <sub>CC</sub> = 5 V 4.5   Driver and control high-level input voltage DIN, FORCEOFF, FORCEON, EN $V_{CC} = 3.3 \text{ V}$ 2   Driver and control low-level input voltage DIN, FORCEOFF, FORCEON, EN $V_{CC} = 5 \text{ V}$ 2.4   Driver and control input voltage DIN, FORCEOFF, FORCEON, EN 0   Receiver input voltage DIN, FORCEOFF, FORCEON 0   Operating free-air temperature SN65C3221 -40	Supply voltage $V_{CC} = 3.3 V$ 3 3.3   V <sub>CC</sub> = 5 V 4.5 5   Driver and control high-level input voltage DIN, FORCEOFF, FORCEON, EN $V_{CC} = 3.3 V$ 2   Driver and control low-level input voltage DIN, FORCEOFF, FORCEON, EN $V_{CC} = 5 V$ 2.4   Driver and control input voltage DIN, FORCEOFF, FORCEON, EN 0   Driver and control input voltage DIN, FORCEOFF, FORCEON 0   Receiver input voltage -25   Operating free-air temperature SN65C3221 -40	VCC = $3.3$ V33.33.6Supply voltageVCC = $5$ V $4.5$ $5$ $5.5$ Driver and control high-level input voltageDIN, FORCEOFF, FORCEON, ENVCC = $3.3$ V $2$ $-25$ Driver and control low-level input voltageDIN, FORCEOFF, FORCEON, EN $0$ $0.8$ Driver and control input voltageDIN, FORCEOFF, FORCEON $0$ $5.5$ Receiver input voltageDIN, FORCEOFF, FORCEON $0$ $5.5$ Receiver input voltage $-25$ $25$ Operating free-air temperature $-40$ $85$

NOTE 4: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V ± 0.5 V.

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP‡	MAX	UNIT	
Ц	Input leakage current	FORCEOFF, FORCEON, EN			±0.01	±1	μΑ
		Auto-powerdown disabled	No load, FORCEOFF and FORCEON at $V_{CC}$		0.3	1	mA
lcc	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
	(T <sub>A</sub> = 25°C)	Auto-powerdown enabled	No load, <del>FORCEOFF</del> at V <sub>CC</sub> , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

NOTE 4: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V ± 0.5 V.



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### DRIVER SECTION

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS			TYP†	MAX	UNIT	
Vон	High-level output voltage	DOUT at $R_L = 3 k\Omega$ to GND,	DIN = GND	5	5.4		V	
VOL	Low-level output voltage	DOUT at $R_L = 3 k\Omega$ to GND,	$DIN = V_{CC}$	-5	-5.4		V	
IIН	High-level input current	$V_{I} = V_{CC}$			±0.01	±1	μA	
۱ <sub>IL</sub>	Low-level input current	V <sub>I</sub> at GND			±0.01	±1	μA	
		$V_{CC} = 3.6 V,$	$V_{O} = 0 V$		±35	±60		
los	Short-circuit output current‡	V <sub>CC</sub> = 5.5 V,	$V_{O} = 0 V$		±35	±90	mA	
r <sub>o</sub>	Output resistance	$V_{CC}$ , V+, and V- = 0 V,	$V_{O} = \pm 2 V$	300	10M		Ω	
1			$V_{O} = \pm 12$ V, $V_{CC} = 3$ V to 3.6 V			±25		
loff	Output leakage current	Output leakage current FORCEOFF = GND		$V_{O} = \pm 10$ V, $V_{CC} = 4.5$ V to 5.5 V			±25	μA

<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V or  $V_{CC}$  = 5 V, and  $T_A$  = 25°C.

<sup>‡</sup> Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V ± 0.5 V.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	-	TEST CONDITIONS			TYP†	MAX	UNIT
			CL = 1000 pF		250			
Maximu (see Fig	im data rate	$R_L = 3 k\Omega$	C <sub>L</sub> = 250 pF,	$V_{CC}$ = 3 V to 4.5 V	1000			kbit/s
(300 1 19	Jure 1)		C <sub>L</sub> = 1000 pF,	1000 pF, $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$				
t <sub>sk(p)</sub>	Pulse skew§	$C_L = 150 \text{ pF}$ to 2500 pF	$R_L = 3 \ k\Omega$ to 7 $k\Omega$ ,	See Figure 2		100		ns
SR(tr)	Slew rate, transition region (see Figure 1)	V <sub>CC</sub> = 3.3 V, R <sub>L</sub> = 3 kΩ to 7 kΩ	C <sub>L</sub> = 150 pF to 1000 pF		18		150	V/µs

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V ± 0.5 V.

#### **ESD** protection

TERM	INAL	TEST CONDITIONS	TVD	
NAME			ITP	UNIT
DOUT	13	НВМ	±15	kV



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#### **RECEIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
VOH	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V <sub>CC</sub> – 0.6 V	$V_{CC} - 0.1 V$		V
VOL	Low-level output voltage	I <sub>OL</sub> = 1.6 mA			0.4	V
N/	Desitive as is a input three held us to as	V <sub>CC</sub> = 3.3 V		1.6	2.4	
VIT+	Positive-going input threshold voltage	$V_{CC} = 5 V$		1.9	2.4	V
	Manual Sector Sector Sector damage and states the sec	V <sub>CC</sub> = 3.3 V	0.6	1.1		
$V_{IT-}$	Negative-going input threshold voltage	$V_{CC} = 5 V$	0.8	1.4		V
V <sub>hys</sub>	Input hysteresis (V <sub>IT+</sub> – V <sub>IT–</sub> )			0.5		V
loff	Output leakage current	FORCEOFF = 0 V		±0.05	±10	μΑ
ri	Input resistance	$V_I = \pm 3 V$ to $\pm 25 V$	3	5	7	kΩ

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

NOTE 4: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V ± 0.5 V.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

	PARAMETER	TEST CONDITIONS	ΜΙΝ ΤΥΡ <sup>†</sup> ΜΑΧ	UNIT
<sup>t</sup> PLH	Propagation delay time, low- to high-level output	C <sub>L</sub> = 150 pF, See Figure 3	150	ns
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	C <sub>L</sub> = 150 pF, See Figure 3	150	ns
ten	Output enable time	$C_L$ = 150 pF, $R_L$ = 3 k $\Omega$ , See Figure 4	200	ns
t <sub>dis</sub>	Output disable time	$C_L$ = 150 pF, $R_L$ = 3 k $\Omega$ , See Figure 4	200	ns
t <sub>sk(p)</sub>	Pulse skew <sup>‡</sup>	See Figure 3	50	ns

<sup>†</sup> All typical values are at  $V_{CC} = 3.3$  V or  $V_{CC} = 5$  V, and  $T_A = 25^{\circ}$ C.

<sup>‡</sup>Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047  $\mu$ F, C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V ± 0.5 V.

#### ESD protection

TERMI	NAL		TVD	
NAME	NAME NO. TEST CONDITIONS		TYP	UNIT
RIN	8	НВМ	±15	kV



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### AUTO-POWERDOWN SECTION

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CO	ONDITIONS	MIN	MAX	UNIT
V <sub>T+(valid)</sub>	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$		2.7	V
V <sub>T-(valid)</sub>	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$	-2.7		V
V <sub>T(invalid)</sub>	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$	-0.3	0.3	V
VOH	INVALID high-level output voltage	$\frac{I_{OH} = -1 \text{ mA}}{FORCEOFF} = V_{CC}$	DN = GND,	V <sub>CC</sub> -0.6		V
V <sub>OL</sub>	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}, \text{FORCEO}$ FORCEOFF = $V_{CC}$	DN = GND,		0.4	V

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

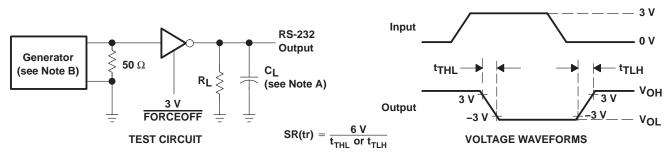
	PARAMETER	MIN TYP <sup>†</sup>	MAX	UNIT
<sup>t</sup> valid	Propagation delay time, low- to high-level output	1		μs
<sup>t</sup> invalid	Propagation delay time, high- to low-level output	30		μs
t <sub>en</sub>	Supply enable time	100		μs

<sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V or  $V_{CC}$  = 5 V, and  $T_A$  = 25°C.



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NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_0$  = 50  $\Omega$ , 50% duty cycle,  $t_f \le 10$  ns,  $t_f \le 10$  ns.



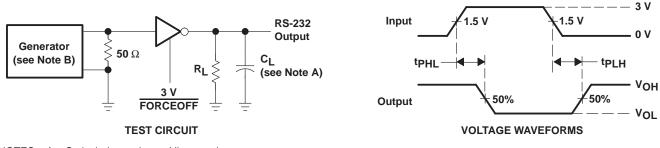
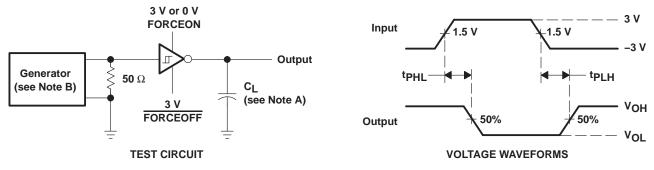




Figure 2. Driver Pulse Skew

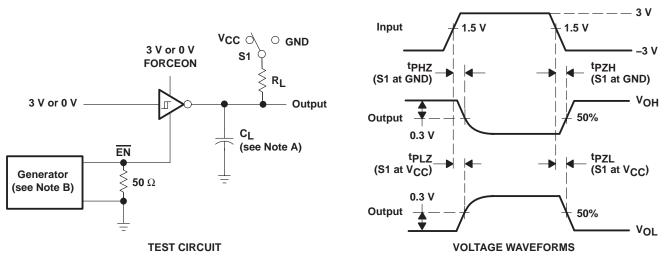


NOTES: A. C<sub>L</sub> includes probe and jig capacitance. B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \le 10$  ns,  $t_f \le 10$  ns.

Figure 3. Receiver Propagation Delay Times



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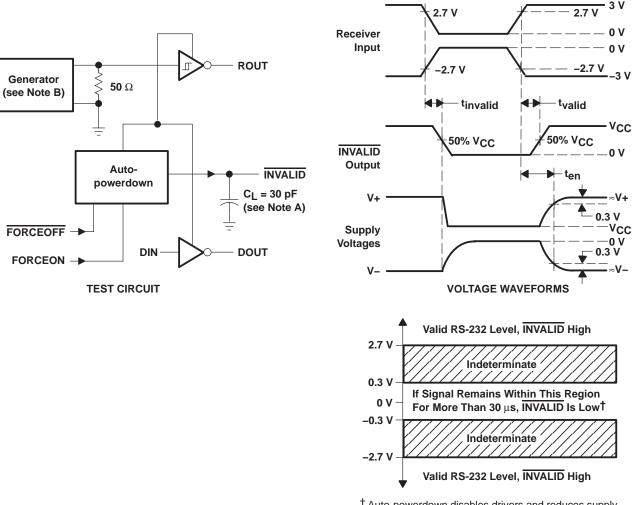
#### PARAMETER MEASUREMENT INFORMATION

- NOTES: A.  $\ensuremath{\mathsf{CL}}$  includes probe and jig capacitance.
  - B. The pulse generator has the following characteristics:  $Z_0 = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.
    - C.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
    - D.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .

#### Figure 4. Receiver Enable and Disable Times



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#### PARAMETER MEASUREMENT INFORMATION

 $^\dagger$  Auto-powerdown disables drivers and reduces supply current to 1  $\mu A.$ 

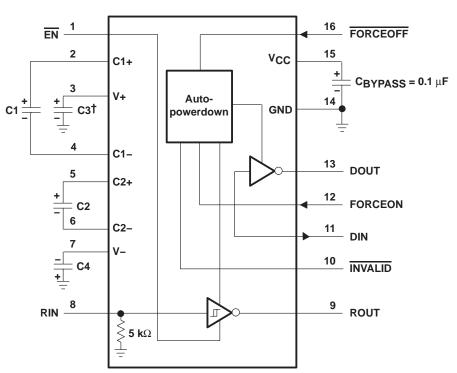
NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.

#### Figure 5. INVALID Propagation Delay Times and Driver Enabling Time



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#### **APPLICATION INFORMATION**

 $^{\dagger}$  C3 can be connected to V<sub>CC</sub> or GND. NOTE A: Resistor values shown are nominal.

VCC VS CALACITOR VALUES									
Vcc	C1	C2, C3, and C4							
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF							

#### V<sub>CC</sub> vs CAPACITOR VALUES





10-Dec-2020

### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65C3221DB	ACTIVE	SSOP	DB	16	80	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221DBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221DBRE4	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PWRE4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN75C3221DBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221DW	PREVIEW	SOIC	DW	16	40	TBD	Call TI	Call TI	0 to 70		
SN75C3221PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221PWE4	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.



# PACKAGE OPTION ADDENDUM

10-Dec-2020

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN65C3221 :

• Automotive: SN65C3221-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

# PACKAGE MATERIALS INFORMATION

Texas Instruments

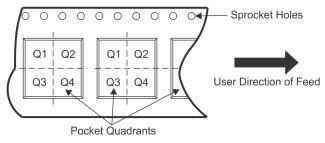
www.ti.com

#### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



All dimensions are nominal <b>Device</b>	1	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65C3221DBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN65C3221PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN75C3221DBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN75C3221PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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# PACKAGE MATERIALS INFORMATION

19-Jun-2021



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65C3221DBR	SSOP	DB	16	2000	853.0	449.0	35.0
SN65C3221PWR	TSSOP	PW	16	2000	853.0	449.0	35.0
SN75C3221DBR	SSOP	DB	16	2000	853.0	449.0	35.0
SN75C3221PWR	TSSOP	PW	16	2000	853.0	449.0	35.0

# **PW0016A**



# **PACKAGE OUTLINE**

## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



# PW0016A

# **EXAMPLE BOARD LAYOUT**

## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# PW0016A

# **EXAMPLE STENCIL DESIGN**

## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

9. Board assembly site may have different recommendations for stencil design.



<sup>8.</sup> Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## **MECHANICAL DATA**

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

### DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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